

# mSATA

## 3TE7 Series with iCell

**Customer:** \_\_\_\_\_  
**Customer**  
**Part Number:** \_\_\_\_\_  
**Innodisk**  
**Part Number:** \_\_\_\_\_  
**Innodisk**  
**Model Name:** \_\_\_\_\_  
**Date:** \_\_\_\_\_

<b>Innodisk Approver</b>	<b>Customer Approver</b>

**Total Solution For  
Industrial Flash Storage**

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## REVISION HISTORY

Revision	Description	Date
1.0	Official Release	July, 2020
1.1	Update Mechanical Drawing	July, 2020
2.0	Add 112 Layers 3D TLC	Jan., 2022
2.1	Update performance table	Dec., 2022
2.2	Add SMART Table	May, 2023
2.3	Revised Pin Assignment (Remove DEVSLP)	May, 2025

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# 1. Product Overview

## 1.1 Introduction of Innodisk mSATA 3TE7

Innodisk mSATA 3TE7 which is designed with mSATA form factor by JEDEC MO-300/MO-300B , supporting SATA III standard (6.0Gb/s), achieves excellent performance up to 4CH standard by cost effective controller with 4CH. Regarding of mechanical interference, Innodisk mSATA 3TE7 absolutely replaces the traditional hard disk and makes personal computer, in any field, smaller and easier.

With Innodisk L<sup>3</sup> FW architecture, combining our signature 4K mapping algorithm L<sup>2</sup> FW architecture with powerful LDPC technology, 3TE7 series has outstanding high IOPS, better data integrity and extended lifespan through reducing the bad block number happening.

For real industrial application, 3TE7 series is built in thermal sensor to monitor the environment temperature. iData Guard, the power loss management mechanism developed by Innodisk, ensures data integrity while power sudden loss happened.

## 1.2 Product View and Models

Innodisk mSATA 3TE7 is available in follow capacities within 3D NAND flash ICs.

[mSATA 3TE7 64GB](#)   [mSATA 3TE7 128GB](#)

[mSATA 3TE7 256GB](#)   [mSATA 3TE7 512GB](#)

[mSATA 3TE7 1TB](#)



**Figure 1: Innodisk mSATA 3TE7**

## 1.3 SATA Interface

Innodisk mSATA 3TE7 supports SATA III(6.0Gb/s) interface, and compliant with SATA I (1.5Gb/s) and SATA II(3.0Gb/s).

## 2. Product Specifications

### 2.1 Capacity and Device Parameters

mSATA 3TE7 with iCell device parameters are shown in Table 1.

**Table 1: Device parameters**

Capacity	LBA	Cylinders	Heads	Sectors	User Capacity(GB)
64GB	117231408	16383	16	63	55.9
	107463888(112-L)				51.2
128GB	234441648	16383	16	63	111.8
256GB	468862128	16383	16	63	223.6
512GB	937703088	16383	16	63	447.1
1TB	1875385008	16383	16	63	894.3

### 2.2 Performance

Burst Transfer Rate: 6.0Gbps

**Table 2: Performance - 64 Layers 3D TLC**

Capacity	Unit	64GB	128GB	256GB	512GB
Sequential ** Read (Q4T1)	MB/s	350	500	520	515
Sequential ** Write (Q4T1)		70	145	295	330
Sustained Sequential Read (Avg.)***		320	400	400	400
Sustained Sequential Write (Avg.)***		65	135	270	300
4KB Random** Read (Q32T1)	IOPS	18,000	28,000	56,000	57,000
4KB Random** Write (Q32T1)		18,000	37,000	66,000	68,000

Note: \* Performance results are measured in Room Temperature with Out-of-Box devices and may varied depend on overall host system setup.

Note: \*\* Performance results are based on CrystalDiskMark 5.1.2 with file size 1000MB.

**Table 3: Performance – 112 Layers 3D TLC**

Capacity	Unit	128GB	256GB	512GB	1TB
Sequential** Read (Q32T1)	MB/s	430	550	550	550
Sequential** Write (Q32T1)		290	480	490	450
Sustained Sequential Read (Avg.)***		350	420	420	400
Sustained Sequential Write (Avg.)***		80	160	310	270
4KB Random** Read (QD32)	IOPS	40,000	75,000	82,000	83,000
4KB Random** Write (QD32)		20,000	40,000	71,000	71,000

Note: \* Performance results are tested in Room Temperature with Out-of-Box devices and may vary depending on overall system setup. In addition, 3TE7 series adopt hybrid mode which enables SLC Cache followed by TLC direct write to strike balance between burst performance and steady overall stability.

Note: \*\* Performance results are based on CrystalDiskMark 6.0.2 with typical tolerance for range from 1% to 10%.

Note: \*\*\* Performance results are based on AIDA 64 with block size 1MB of Linear Write Test Item

## 2.3 Electrical Specifications

### 2.3.1 Power Requirement

**Table 4: Innodisk mSATA 3TE7 Power Requirement**

Item	Symbol	Rating	Unit
Input voltage	V <sub>IN</sub>	+3.3 DC +- 5%	V

### 2.3.2 Power Consumption

**Table 5: Typical Power Consumption**

Mode	Power Consumption (W)
Read (RMS)	1.4
Write (RMS)	1.7
Idle (RMS)	0.7
Peak	2.9

## 2.4 Environmental Specifications

### 2.4.1 Temperature Ranges

**Table 6: Temperature range for mSATA 3TE7**

Temperature	Range
Operating	Standard Grade: 0°C to +70°C
	Industrial Grade: -40°C to +85°C
Storage	-40°C to +85°C

### 2.4.2 Humidity

Relative Humidity: 10-95%, non-condensing

### 2.4.3 Shock and Vibration

**Table 7: Shock/Vibration Testing for mSATA 3TE7**

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 60068-2-6
Mechanical Shock	Duration: 0.5ms, 1500 G, 3 axes	IEC 60068-2-27

### 2.4.4 Mean Time between Failures (MTBF)

Table 7 summarizes the MTBF prediction results for various mSATA 3TE7 configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- **Failure Rate:** The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.
- **Mean Time between Failures (MTBF):** A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

**Table 8: mSATA 3TE7 MTBF**

Product	Condition	MTBF (Hours)
Innodisk mSATA 3TE7	Telcordia SR-332 GB, 25°C	>3,000,000

## 2.5 CE and FCC Compatibility

mSATA 3TE7 with iCell conforms to CE and FCC requirements.

## 2.6 RoHS Compliance

mSATA 3TE7 with iCell is fully compliant with RoHS directive.

## 2.7 Reliability

Parameter	Value	
Flash endurance	3,000 P/E cycles	
Error Correct Code	Support	
Data Retention	Under 40°C: 1 Year at NAND Life End	
<b>TBW* (Total Bytes Written)</b> Units: TB		
Capacity	Sequential workload	Client workload
64GB	170	75
128GB	341	150
256GB	682	300
512GB	1364	600
1TB	2727	1200
<p>* Note:</p> <ol style="list-style-type: none"> <li>1. Sequential: Mainly sequential write, tested by Vdbench.</li> <li>2. Client: Follow JESD218 Test method and JESD219A Workload, tested by ULINK. (The capacity lower than 64GB client workload is not specified in JEDEC219A, the values are estimated.)</li> <li>3. Based on out-of-box performance.</li> </ol>		

## 2.8 Transfer Mode

mSATA 3TE7 support following transfer mode:

Serial ATA III 6.0Gbps

Serial ATA II 3.0Gbps

Serial ATA I 1.5Gbps

## 2.9 Pin Assignment

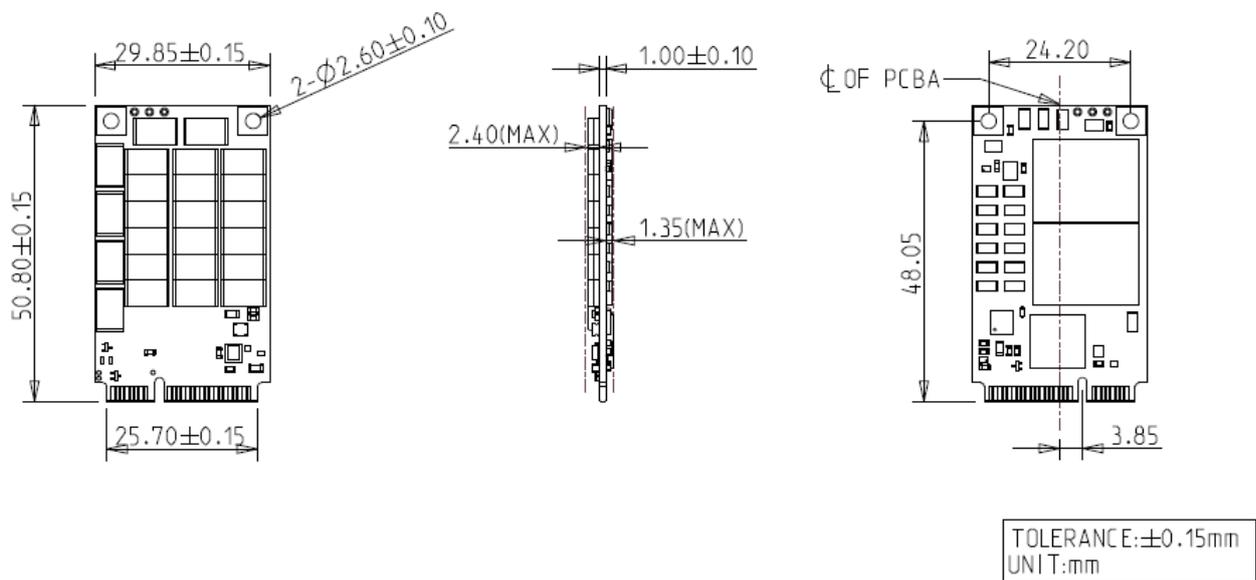
Innodisk mSATA 3TE7 uses a standard SATA pin-out. See Table 8 for mSATA 3TE7 pin assignment.

**Table 9: Innodisk mSATA 3TE7 Pin Assignment**

Signal Name	Pin #	Pin #	Signal Name
GND	51	52	+3.3V
DAS	49	50	GND

NC	47	48	NC
NC	45	46	NC
NC	43	44	Reserved
+3.3V	41	42	NC
+3.3V	39	40	GND
GND	37	38	NC
GND	35	36	NC
RX+	33	34	GND
RX-	31	32	NC
GND	29	30	NC
GND	27	28	NC
TX-	25	26	GND
TX+	23	24	+3.3V
GND	21	22	NC
NC	19	20	NC
NC	17	18	GND
GND	15	16	NC
NC	13	14	NC
NC	11	12	NC
GND	9	10	NC
NC	7	8	NC
NC	5	6	NC
NC	3	4	GND
NC	1	2	+3.3V

## 2.10 Mechanical Dimensions



Note: Actual iCell quantities may vary depend on SSD capacities

## 2.11 Assembly Weight

An Innodisk mSATA 3TE7 within flash ICs, 32GB's weight is 8 grams approximately.

## 2.12 Seek Time

Innodisk mSATA 3TE7 is not a magnetic rotating design. There is no seek or rotational latency required.

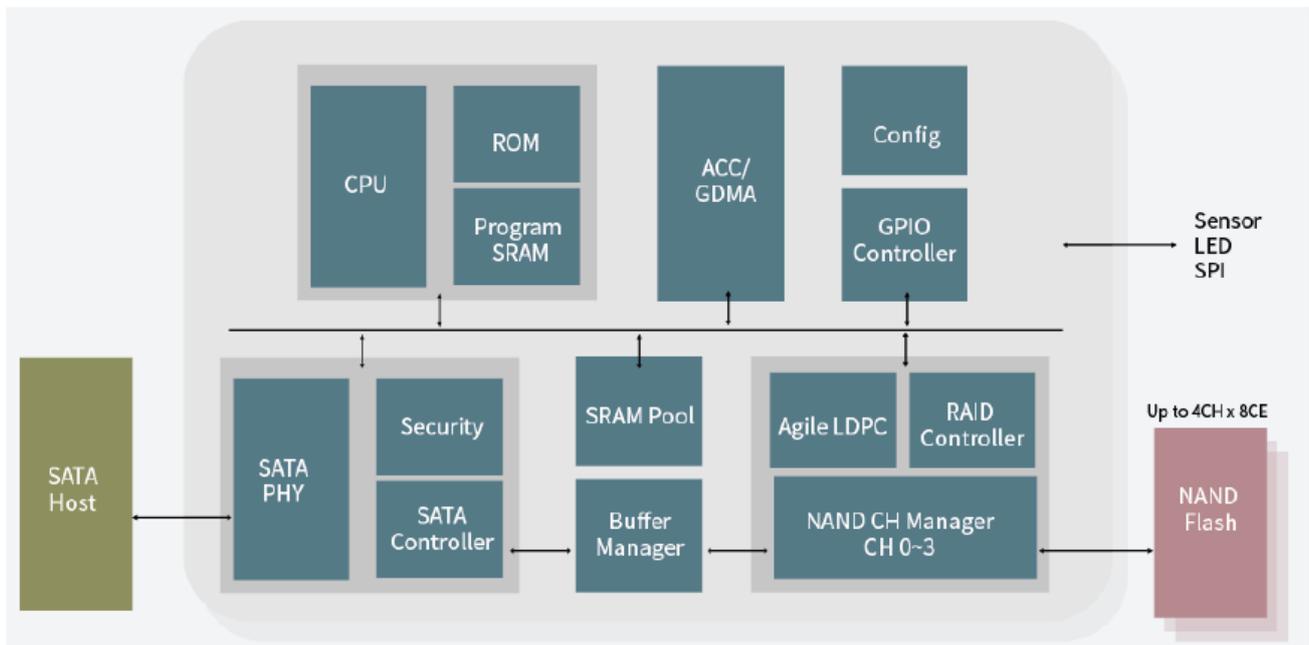
## 2.13 NAND Flash Memory

Innodisk mSATA 3TE7 uses 3D TLC NAND flash memory, with 3,000 program & erase cycles, which is non-volatility, high reliability and high speed memory storage.

# 3. Theory of Operation

## 3.1 Overview

Figure 2 shows the operation of Innodisk mSATA 3TE7 from the system level, including the major hardware blocks.



**Figure 2: Innodisk mSATA 3TE7 Block Diagram**

Innodisk mSATA 3TE7 integrates a SATA III controller and NAND flash memories. Communication with the host occurs through the host interface, using the standard ATA protocol. Communication with the flash device(s) occurs through the flash interface.

## 3.2 SATA III Controller

Innodisk mSATA 3TE7 is designed with a SATA III 6.0Gbps (Gen. 3) controller. The Serial ATA physical, link and transport layers are compliant with Serial ATA Gen 1, Gen 2 and Gen 3 specification (Gen 3 supports 1.5Gbps/3.0Gbps/6.0Gbps data rate). The controller has 4 channels for flash interface.

## 3.3 Error Detection and Correction

Innodisk mSATA 3TE7 is designed with hardware LDPC ECC engine with hard-decision and Soft-decision decoding. Low-density parity-check (LDPC) codes have excellent error correcting Performance close to the Shannon limit when decoded with the belief-propagation (BP) algorithm

using soft-decision information.

### 3.4 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the **erase cycle limit** or **write endurance limit** and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

Innodisk mSATA 3TE7 uses a static wear-leveling algorithm to ensure that consecutive writes of a specific sector are not written physically to the same page/block in the flash. This spreads flash media usage evenly across all pages, thereby extending flash lifetime.

### 3.5 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may develop during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management, Bad Blocks replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit.

### 3.6 iData Guard

Innodisk's iData Guard is a comprehensive data protection mechanism that functions before and after a sudden power outage to SSD. Low-power detection terminates data writing before an abnormal power-off, while table-remapping after power-on deletes corrupt data and maintains data integrity. Innodisk's iData Guard provides effective power cycling management, preventing data stored in flash from degrading with use.

### 3.7 Garbage Collection

Garbage collection is used to maintain data consistency and perform continual data cleansing on SSDs. It runs as a background process, freeing up valuable controller resources while sorting good data into available blocks, and deleting bad blocks. It also significantly reduces write operations to the drive, thereby increasing the SSD's speed and lifespan.

### 3.8 Trim

The Trim command is designed to enable the operating system to notify the SSD which pages no longer contain valid data due to erases either by the user or operating system itself. During a delete operation, the OS will mark the sectors as free for new data and send a Trim command to the SSD to mark them as not containing valid data. After that the SSD knows not to preserve the

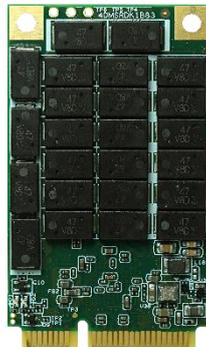
contents of the block when writing a page, resulting in less write amplification with fewer writes to the flash, higher write speed, and increased drive life.

### 3.9 iPower Guard

iPower Guard technology is a set of preventive measures that protect the SSD in an unstable power supply environment. This comprehensive package comprises safeguards for startup and shutdown to maintain device performance and ensure data integrity.

### 3.10 iCell

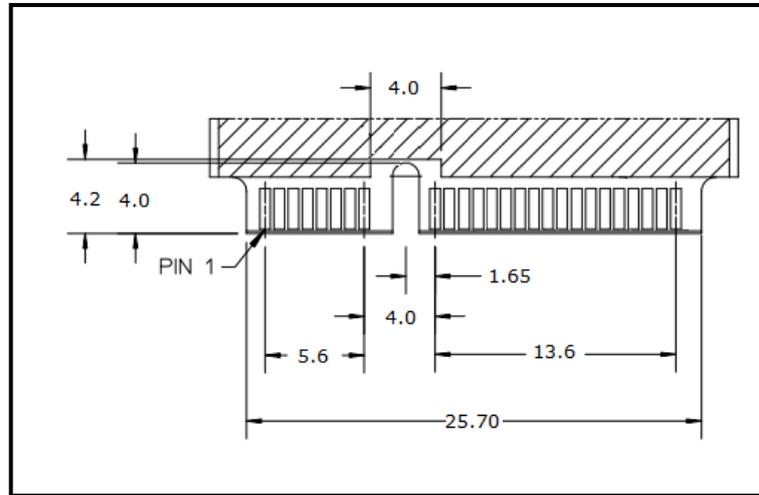
iCell circuit is designed on this board to withstand unexpected power lost scenario. With precious seconds iCell provided, our FW is capable to flush all critical data into Flash from volatile DRAM or SRAM caches.



Note: Actual iCell quantities may vary depend on SSD capacities

# 4. Installation Requirements

## 4.1 mSATA 3TE7 Pin Directions



**Figure 3: Signal Segment and Power Segment**

## 4.2 Electrical Connections for mSATA 3TE7

A Serial ATA device may be either directly connected to a host or connected to a host through an adaptor card. The SATA interface has a separate connector for the power supply. Please refer to the pin description for further details.

## 4.3 Device Drive

No additional device drives are required. The Innodisk mSATA 3TE7 can be configured as a boot device.

# 5. SMART Feature Set

Innodisk 3TE7 series support the SMART command set and defines some vendor-specific data to report SMART attributes of SSD.

**Table 10: SMART command**

Value	Command	Value	Command
D0h	Read Data	D5h	Read Log
D1h	Read Attribute Threshold	D6h	Return Status
D2h	Enable/Disable Auto save	D8h	Enable SMART Operations
D3h	Save Attribute Values	D9h	Disable SMART Operations
D4h	Execute OFF-LINE Immediate	DAh	Return Status

## 5.1 SMART Attributes

Innodisk 3TE7 series SMART data attributes are listed in following table.

**Table 11: SMART attribute**

Attribute ID (hex)	Value	Raw Attribute Value						Rsv	Attribute Name
		LSB	MSB						
05	X	LSB	MSB	00	00	00	00	00	Later Bad
09	LSB	LSB	MSB	00	00	00	00	00	Power-On hours Count
0C	LSB	LSB	MSB	00	00	00	00	00	Drive Power Cycle Count
A3	X	LSB			MSB	00	00	00	Total Bad Block Count
A5	LSB	LSB			MSB	00	00	00	Max Erase count
A7	LSB	LSB			MSB	00	00	00	Avg Erase count
A9	LSB	LSB	00	00	00	00	00	00	Device Life
AA	X	LSB	MSB	00	00	00	00	00	Spare Block Count
AB	LSB	LSB	MSB	00	00	00	00	00	Program fail count
AC	LSB	LSB	MSB	00	00	00	00	00	Erase fail count
C0	LSB	LSB	MSB	00	00	00	00	00	Unexpected Power Loss Count
C2	LSB			MIN		MAX	00	00	Temperature
E5		ID 0	ID 1	ID 2	ID 3	ID 4	ID 5		Flash ID

EB			MSB	LSB	MSB	LSB	MSB	LSB	Later bad block info (Read/Write/Erase)
F1	00	LSB			MSB	00	00	00	Total LBA written(LBA=32MB)
F2	00	LSB			MSB	00	00	00	Total LBA read(LBA=32MB)

## 6. Part Number Rule

CODE	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21
	D	E	M	S	R	-	C	1	2	D	K	1	E	C	A	Q	F	P	-	X	X
<b>Definition</b>																					
<b>Code 1<sup>st</sup> (Disk)</b>											<b>Code 13<sup>th</sup> (Flash Mode)</b>										
D : Disk											E: 64 layers 3D TLC										
											K: 112 layers 3D TLC										
<b>Code 2<sup>nd</sup> (Feature Set)</b>											<b>Code 14<sup>th</sup> (Operation Temperature)</b>										
E: Embedded											C: Standard Grade (0°C~ +70°C)										
											W: Industrial Grade (-40°C~ +85°C)										
<b>Code 3<sup>rd</sup>~ 5<sup>th</sup> (Form Factor)</b>											<b>Code 15<sup>th</sup> (Internal control)</b>										
MSR: mSATA Regular											1/A: PCB version										
<b>Code 7<sup>th</sup> ~9<sup>th</sup> (Capacity)</b>											<b>Code 16<sup>th</sup> (Channel of data transfer)</b>										
32G: 32GB											S: Single Channel										
64G: 64GB											D: Dual Channels										
A28: 128GB											Q: Quad Channels										
B56: 256GB											<b>Code 17<sup>th</sup> (Flash Type)</b>										
C12: 512GB											F: Toshiba 3D TLC										
01T: 1TB											<b>Code 18<sup>th</sup> (Flash Type)</b>										
											P: iCell technology incorporated										
<b>Code 10<sup>th</sup> ~12<sup>th</sup> (Controller)</b>											<b>Code 19<sup>th</sup>~21<sup>th</sup> (Customized Code)</b>										
DK1: SATA 3TE7																					